

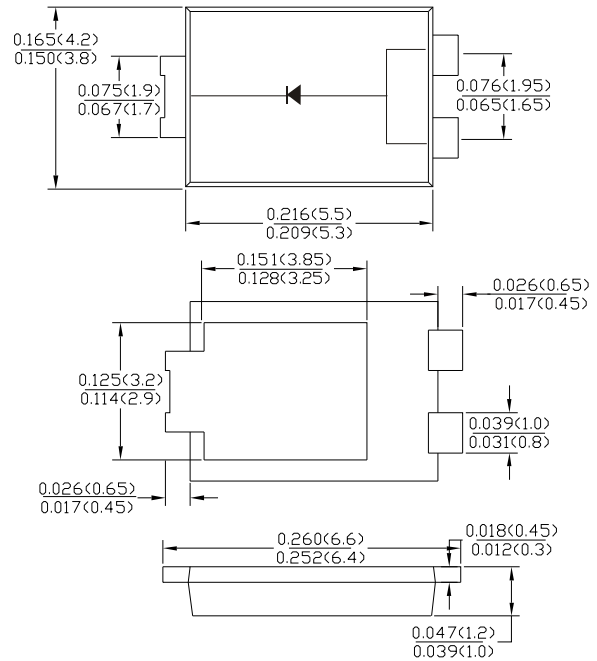
### Features

- Schottky Barrier Chip
- High Thermal Reliability
- Patented Super Barrier Rectifier Technology
- High Forward Surge Capability
- Ultra Fow Power Loss,High Efficiency
- Excellent High Temperature Stability

### Mechanical Data

- Case: TO-277B, molded plastic
- Terminals:Plated Leads Solderable per MIL-STD-202,Method 208
- Polarity:Cathode Band
- Mounting Position:Any
- Marking:Type Number
- Lead Free:For RoHS/Lead Free Version

### TO-277B



dimensions in inches and (millimeters)

### Maximum Ratings and Electrical Characteristics @T<sub>A</sub> =25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbol	SR1045L	SR1050L	SR1060L	SR1080L	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>					
Working Peak Reverse Voltage	V <sub>RWM</sub>	45	50	60	80	V
DC blocking voltage	V <sub>DC</sub>					
RMS Rectified Voltage	V <sub>R(RMS)</sub>	28	35	42	56	V
Average Rectified Output Current (Note1)	I <sub>F(AV)</sub>	10				A
Non-Repetitive Peak Forward Surge 8.3ms Single Half Sine-Wave Superimposed on rated load (JEDEC Method) (Note2)	I <sub>FSM</sub>	275				A
I <sup>2</sup> t Rating for Fusing (t < 8.3ms)	I <sup>2</sup> t	313.844				A <sup>2</sup> s
Forward Voltage Drop T <sub>A</sub> =25°C @ I <sub>F</sub> =10A	V <sub>FM</sub>	0.42	0.45	0.50	0.75	V
Peak Reverse Current T <sub>A</sub> =25°C At Rated DC Blocking Voltage T <sub>A</sub> =100°C	I <sub>R</sub>	0.3 15				mA
Typical Thermal Resistance Junction to Ambient	R <sub>θJA</sub> R <sub>θJL</sub>	80 15				°C/W
Operating junction temperature range	T <sub>J</sub>	-55 to +150				°C
storage temperature range	T <sub>STG</sub>	-55 to +150				°C

Note: 1. Valid Provided that are kept at ambient temperature at a distance of 9.5mm from the case.

2. Fr-4pcb. 2oz. Copper, minimum recommend pad layout .18.8mm×14.4. Anode pad dimensions 5.6mm×14.4mm.

# SR1045L THRU SR1080L

## 10.0A Surface Mount Schottky Barrier Rectifiers

Fig.1 - Forward Current Derating Curve

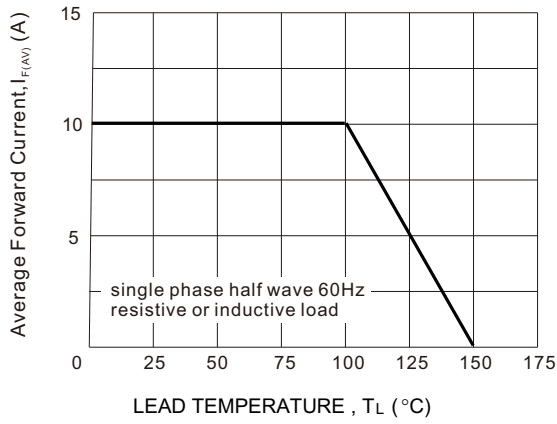


Fig.2 : Instantaneous Forward Voltage

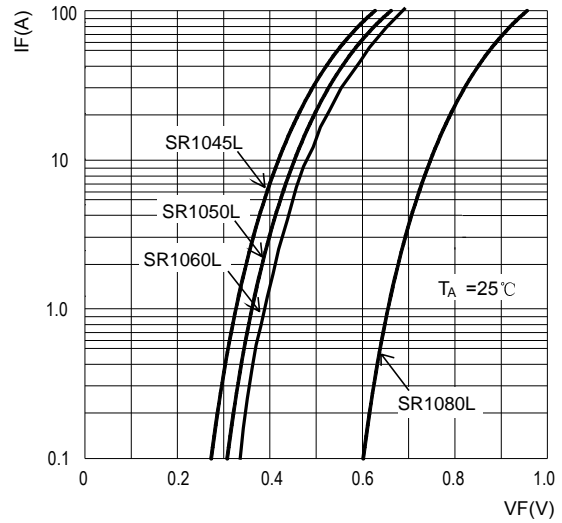


Fig.3: Surge Forward Current Capacity

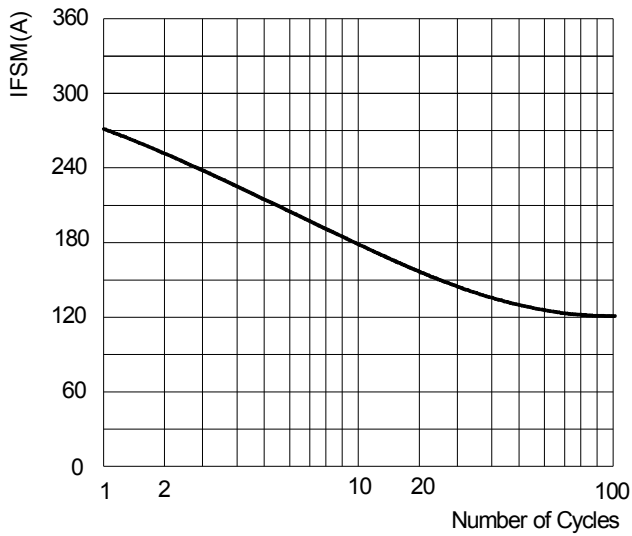


Fig.4: Typical Reverse Characteristics

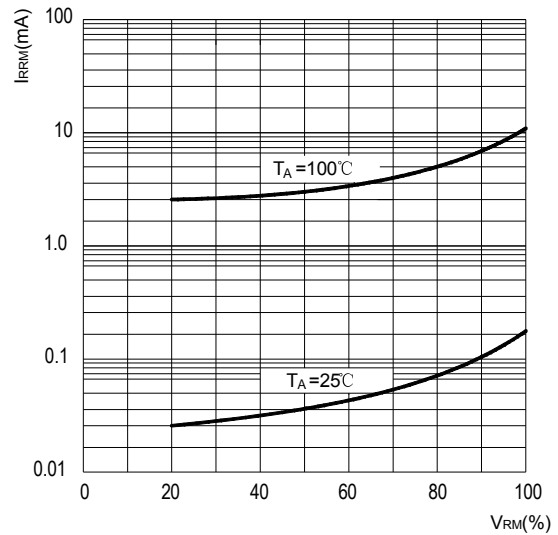


FIG.5 MOUNTING PAD LAYOUT

